256 k High Speed SRAM (32-kword × 8-bit)

# **HITACHI**

#### **Features**

• High speed: Fast access time 15/20 ns (max)

Low Power

Standby: 15 µW (typ) (L-version) Operation: 675/600 mW (typ)

• Single 5 V supply

Completely static memory
 No clock or timing strobe required

• Equal access and cycle times

• Common data input and output: Three state output

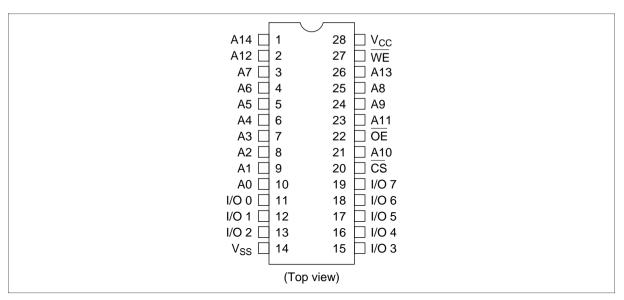
• Directly TTL compatible: All inputs and outputs

## **Ordering Information**

Type No.	Access Time	Package
HM62832UHP-15 HM62832UHP-20	15 ns 20 ns	300-mil 28-pin plastic DIP (DP-28NA)
HM62832UHLP-15 HM62832UHLP-20	15 ns 20 ns	_
HM62832UHJP-15 HM62832UHJP-20	15 ns 20 n	300-mil 28-pin plastic SOJ (CP-28DN)
HM62832UHLJP-15 HM62832UHLJP-20	15 ns 20 ns	_



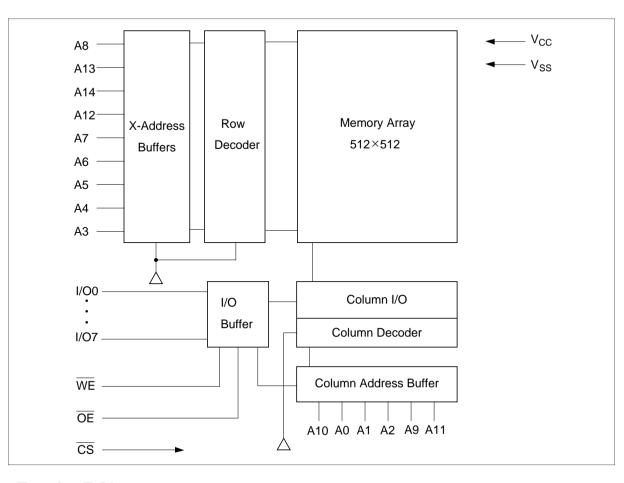
#### **Pin Arrangement**



## **Pin Description**

Pin name	Function
A0 – A14	Address
I/O0 – I/O7	Input/output
CS	Chip select
WE	Write enable
ŌĒ	Output enable
V <sub>cc</sub>	Power supply
V <sub>SS</sub>	Ground

## **Block Diagram**



#### **Function Table**

CS	ŌĒ	WE	Mode	V <sub>cc</sub> Current	I/O Pin	Ref. Cycle
Н	Χ	Х	Standby	I <sub>SB</sub> , I <sub>SB1</sub>	High-Z	
L	L	Н	Read	I <sub>cc</sub>	Dout	Read cycle 1, 2, 3
L	Н	L	Write	I <sub>cc</sub>	Din	Write cycle 1
L	L	L	Write	I <sub>cc</sub>	Din	Write cycle 2

Note: X:H or L

## **Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Supply voltage <sup>*1</sup>	V <sub>cc</sub>	-0.5 <sup>*2</sup> to +7.0	V
Voltage on any pin relative to V <sub>ss</sub> *1	V <sub>T</sub>	$-0.5^{*2}$ to V <sub>CC</sub> + 0.5	V
Power dissipation	P <sub>T</sub>	1.0	W
Operating temperature	Topr	0 to +70	°C
Storage temperature	Tstg	-55 to +125	°C
Storage temperature under bias	Tbias	-10 to +85	°C

Notes: 1. With respect to V<sub>ss</sub>

2.  $V_{CC}$  and  $V_{T}$  min = -2.5 V for pulse width  $\leq$  10 ns

#### **Recommended DC Operating Conditions** (Ta = 0 to +70°C)

Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage	V <sub>cc</sub>	4.5	5.0	5.5	V
	V <sub>SS</sub>	0	0	0	V
Input high (logic 1) voltage	V <sub>IH</sub>	2.2		V <sub>cc</sub> + 0.5	V
Input low (logic 0) voltage	V <sub>IL</sub>	-0.5 <sup>*1</sup>	<del></del>	0.8	V

Note: 1.  $V_{IL}$  min = -2.0 V for pulse width  $\leq$  10 ns

**DC Characteristics** (Ta = 0 to +70°C,  $V_{CC} = 5 \text{ V} \pm 10\%$ ,  $V_{SS} = 0 \text{ V}$ )

Parameter	Symbol	Min	Typ⁵¹	Max	Unit	Test Conditions
Input leakage current	I <sub>u</sub>	_	_	2.0	μΑ	$V_{CC} = 5.5 \text{ V}$ Vin = $V_{SS}$ to $V_{CC}$
Output leakage current	I <sub>LO</sub>	_		2.0	μΑ	$\overline{CS} = V_{IH}$ $V_{I/O} = V_{SS}$ to $V_{CC}$
Operating V <sub>cc</sub> current	I <sub>CC1</sub> (-15)*3	_	135	170	mA	min cycle*2
	I <sub>CC2</sub> (-15)	_	100	120	mA	2x min cycle
	I <sub>CC1</sub> (-20)	_	120	150	mA	min cycle
	I <sub>CC2</sub> (-20)		90	110	mA	2x min cycle
Standby V <sub>cc</sub> current	I <sub>SB</sub> (-15)	_	40	60	mA	CS = V <sub>IH</sub> , min cycle
	I <sub>SB</sub> (-20)	_	30	50		
Standby V <sub>cc</sub> current (1)	I <sub>SB1</sub> (L-version)	_	0.02	2.0	mA	$\overline{\text{CS}} \ge \text{V}_{\text{CC}} - 0.2 \text{ V}$ $0 \text{ V} \le \text{Vin} \le 0.2 \text{ V or}$ $\text{V}_{\text{CC}} - 0.2 \text{ V} \le \text{Vin}$
		_	0.003	0.1		_
Output low voltage	V <sub>OL</sub>	_		0.4	V	I <sub>OL</sub> = 8 mA
Output high voltage	V <sub>OH</sub>	2.4	_	_	V	$I_{OH} = -4.0 \text{ mA}$

Notes: 1. Typical values are at  $V_{cc} = 5.0 \text{ V}$ ,  $Ta = 25^{\circ}\text{C}$  and not guaranteed.

- 2.  $\overline{CS} = V_{IL}$ , lout = 0 mA
- 3. Access time version

**Capacitance** (Ta = 25°C, f = 1.0 MHz)<sup>\*1</sup>

Parameter	Symbol	Min	Тур	Max	Unit	Test Conditions
Input capacitance	Cin	_	_	6	pF	Vin = 0 V
Output capacitance	Cout	_	<u> </u>	10	pF	V <sub>I/O</sub> = 0 V

Note: 1. This parameter is sampled and not 100% tested.

**AC Characteristics** (Ta = 0 to  $+70^{\circ}$ C,  $V_{CC} = 5 \text{ V} \pm 10\%$ , unless otherwise noted.)

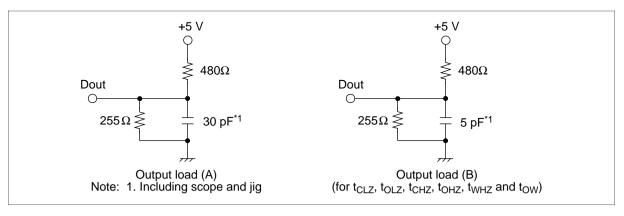
#### **Test Conditions**

Input pulse levels: V<sub>ss</sub> to 3.0 V

• Input rise and fall time: 4 ns

• Input and Output timing reference levels: 1.5 V

Output load: See figures

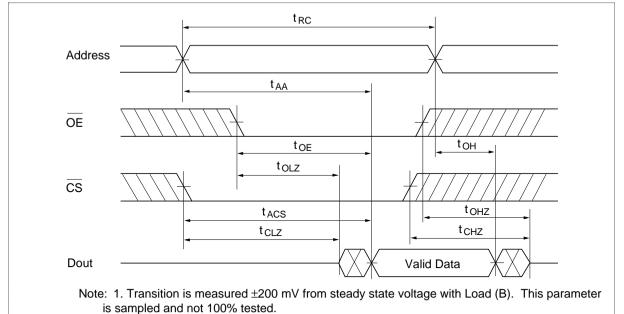


#### **Read Cycle**

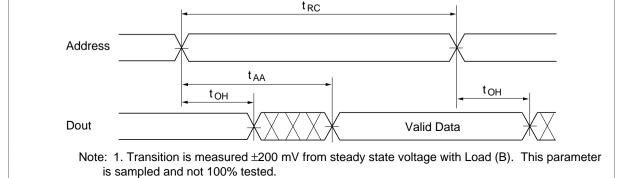
		HM62832UH-15		HM62832UH-20		
Parameter	Symbol	Min	Max	Min	Max	Unit
Read cycle time	t <sub>RC</sub>	15	_	20	_	ns
Address access time	t <sub>AA</sub>	_	15	_	20	ns
Chip select access time	t <sub>ACS</sub>	_	15		20	ns
Chip selection to output in low-Z	t <sub>CLZ</sub> *1	3	_	3	_	ns
Output enable to output valid	t <sub>OE</sub>	_	8	_	10	ns
Output enable to output in low-Z	t <sub>oLZ</sub> *1	0	_	0		ns
Chip deselection to output in high-Z	t <sub>CHZ</sub> *1	0	7	0	10	ns
Chip disable to output in high-Z	t <sub>OHZ</sub> *1	0	7	0	10	ns
Output hold from address change	t <sub>oh</sub>	3	_	3	_	ns

Note: 1. Transition is measured ±200 mV from steady state voltage with Load (B). This parameter is sampled and not 100% tested.

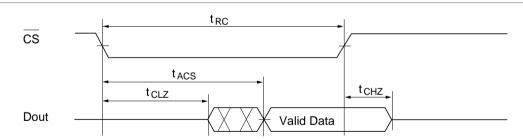
#### Read Timing Waveform $(1)^{*1} (\overline{WE} = V_{IH})$



## Read Timing Waveform (2) \*1 ( $\overline{WE} = V_{IH}$ , $\overline{CS} = V_{IL}$ , $\overline{OE} = V_{IL}$ )



#### Read Timing Waveform (3) \*1, \*2 ( $\overline{WE} = V_{IH}, \overline{OE} = V_{II}$ )



Notes: 1. Transition is measured ±200 mV from steady state voltage with Load (B). This parameter is sampled and not 100% tested.

2. Address valid prior to or coincident with  $\overline{\text{CS}}$  transition low.

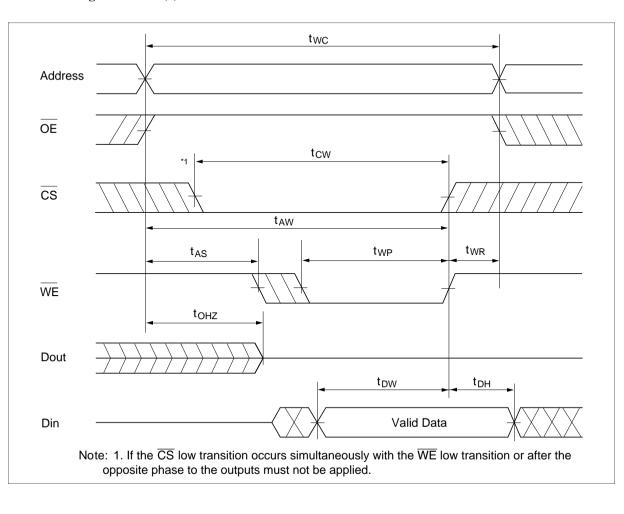
#### Write Cycle

		HM62832UH-15		HM62832UH-20		
Parameter	Symbol	Min	Max	Min	Max	Unit
Write cycle time	t <sub>wc</sub>	15	_	20	_	ns
Chip selection to end of write	t <sub>cw</sub>	10		12	_	ns
Address valid to end of write	t <sub>AW</sub>	13	_	15	_	ns
Address setup time	t <sub>AS</sub>	0		0	_	ns
Write pulse width <sup>*2</sup>	t <sub>WP</sub>	10	_	12	_	ns
Write recovery time <sup>*3</sup>	t <sub>WR</sub>	0	_	0	_	ns
Output disable to output in high-Z*1, 4	t <sub>OHZ</sub>	0	7	0	10	ns
Write to output in high-Z*1, 4	t <sub>WHZ</sub>	0	7	0	10	ns
Data to write time overlap	t <sub>DW</sub>	8	<del></del>	10	_	ns
Data hold from write time*6	t <sub>DH</sub>	0	_	0	_	ns
Output active from end of write *1,6	t <sub>ow</sub>	3	<del></del>	3	_	ns
Output hold from address change *5	t <sub>OH</sub>	3	_	3	_	ns

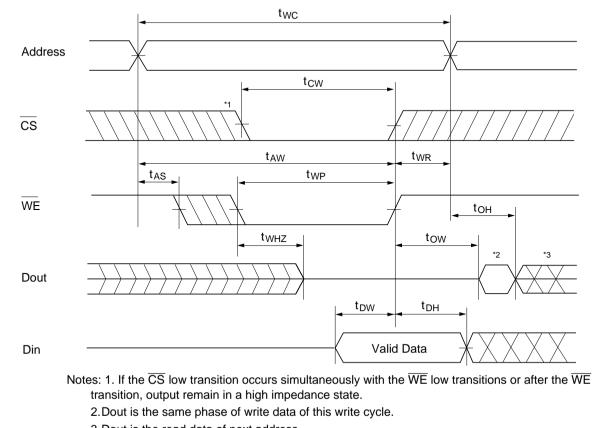
Notes: 1. Transition is measured ±200 mV from high impedance voltage with Load (B). This parameter is sampled and not 100% tested.

- 2. A write occurs during the overlap  $(t_{WP})$  to a low  $\overline{CS}$  and a low  $\overline{WE}$ .
- 3.  $t_{WR}$  is measured from the earlied or  $\overline{CS}$  or  $\overline{WE}$  going high to the end of write cycle.
- 4. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.
- 5. Dout is the same phase of write data of this write cycle.
- 6. If  $\overline{\text{CS}}$  is low during this priod, I/O pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.

#### Write Timing Waveform (1)



Write Timing Waveform (2) (OE low Fixed)\*4



- 3. Dout is the read data of next address.
- 4. WE must be high during all address transition except when device is disable with CS.

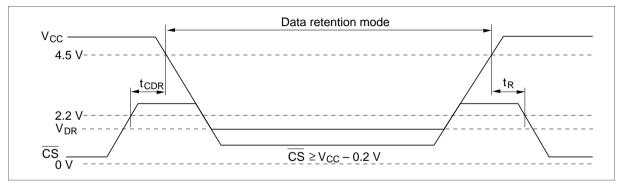
## **Low V**<sub>CC</sub> **Data Retention Characteristics** ( $Ta = 0 \text{ to } +70^{\circ}\text{C}$ )

This characteristics is guaranteed only for L-version.

Parameter	Symbol	Min	Тур	Max	Unit	<b>Test Conditions</b>
V <sub>cc</sub> for data retention	$V_{DR}$	2	_	_	V	$\overline{\text{CS}} \ge \text{V}_{\text{CC}} - 0.2\text{V},$ $\text{Vin} \ge \text{V}_{\text{CC}} - 0.2\text{ V or}$ $0\text{ V} < \text{Vin} \le 0.2\text{ V}$
Data retention current	I <sub>CCDR</sub>	_	2	50 <sup>*1</sup>	μΑ	_
Chip deselect to data retention time	t <sub>CDR</sub>	0	<del></del>	_	ns	_
Operation recovery time	t <sub>R</sub>	5	_	_	ms	_

Note: 1.  $V_{CC} = 3.0 \text{ V}$ 

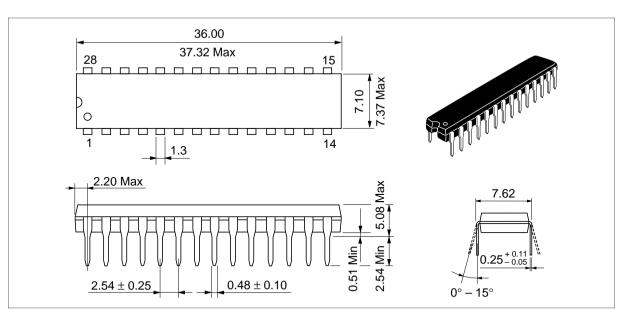
#### Low $V_{cc}$ Data Retention Timing Waveform



#### **Package Dimensions**

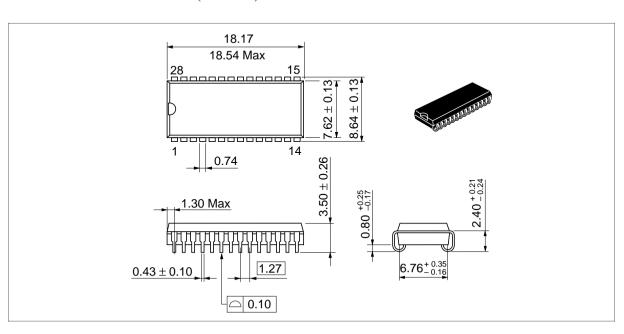
#### HM62832UHP/UHLP Series (DP-28NA)

Unit: mm



#### HM62832UHJP/UHLJP Series (CP-28DN)

Unit: mm



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